Apacer

The Most **Reliable** Storage For Industries

UH110-UFM1





Apacer

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Overview

Apacer's UH110-UFM1 is a high performance, embedded solid state drive (SSD) designed to replace a conventional IDE hard disk drive. Utilizing 3D NAND, UH110-UFM1 can be plugged into a standard Embedded USB connector commonly found in desktops, portable PC systems and industrial PC systems. This product is well suited for embedded flash storage applications offering new and expanded functionality as well as more cost-effective designs, better performance and increased reliability.



Feature

- · Adopts advanced LDPC ECC engine with 3D NAND SLC-liteX technology to improve reliability
- · Global Wear Leveling
- · Flash bad-block management
- · 4K Page Mapping
- · S.M.A.R.T.
- · Hyper Cache Technology
- · SMART Read RefreshTM

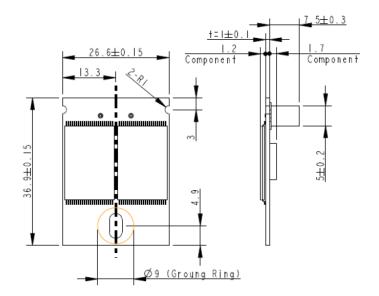


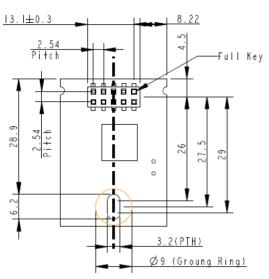
Specifications

ModelUH110-UFM1InterfaceUSB 2.0Connector10-pin (2x5) female header in 2.54mmForm FactorUSB Disk ModuleNAND Flash Type3D TLCCapacity8GB~32GBExternal DRAMNoSustained Read Performance (MB/sec)Up to 41Sustained Write Performance (MB/sec)Up to 25ECC EngineLow-Density Parity-Check (LDPC) CodeIOPS (4K Random Write)500Standard Operating Temperature (°C)0~+70Extended Operating Temperature (°C)-40~+85Storage Temperature (°C)-40~100HousingNoH/W Write ProtectNoScrew HoleYes
Connector 10-pin (2x5) female header in 2.54mm Form Factor USB Disk Module NAND Flash Type 3D TLC Capacity 8GB~32GB External DRAM No Sustained Read Performance (MB/sec) Up to 41 Sustained Write Performance (MB/sec) ECC Engine Low-Density Parity-Check (LDPC) Code IOPS (4K Random Write) 500 Standard Operating Temperature (°C) Extended Operating Temperature (°C) -40~+85 Storage Temperature (°C) Housing No H/W Write Protect
Form Factor NAND Flash Type 3D TLC Capacity 8GB~32GB External DRAM No Sustained Read Performance (MB/sec) Up to 41 Sustained Write Performance (MB/sec) ECC Engine Low-Density Parity-Check (LDPC) Code IOPS (4K Random Write) Standard Operating Temperature (°C) Extended Operating Temperature (°C) Storage Temperature (°C) Housing H/W Write Protect No
NAND Flash Type Capacity External DRAM No Sustained Read Performance (MB/sec) ECC Engine Low-Density Parity-Check (LDPC) Code IOPS (4K Random Write) Standard Operating Temperature (°C) Extended Operating Temperature (°C) Storage Temperature (°C) Housing H/W Write Protect No
Capacity External DRAM No Sustained Read Performance (MB/sec) Sustained Write Performance (MB/sec) ECC Engine Low-Density Parity-Check (LDPC) Code IOPS (4K Random Write) Standard Operating Temperature (°C) Extended Operating Temperature (°C) Storage Temperature (°C) Housing H/W Write Protect No
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Standard Operating Temperature (°C) Extended Operating Temperature (°C) -40 ~ + 85 Storage Temperature (°C) Housing No No No
Extended Operating Temperature (°C) -40 ~ +85 Storage Temperature (°C) Housing No No No
Storage Temperature (°C) Housing No H/W Write Protect No
Housing No H/W Write Protect No
H/W Write Protect No
Screw Hole Yes
Cable-less Solution No
Thermal sensor No
Operation: 50G/11ms (compliant with MIL-STD-202G) Non-operation: 1500G/0.5ms (compliant with MIL-STD-883K)
Vibration Operation: 7.69 Grms, 20~2000 Hz/random (compliant with MIL-STD-810G) Non-operation: 4.02 Grms, 15~2000 Hz/random (compliant with MIL-STD-810G)
Operating Voltage 5.0 V ± 5%
Power Consumption Active mode: 95 mA; Idle mode: 70 mA
Dimension (L x W x H) 36.9 mm x 26.6 mm x 9.7 mm
MTBF (hours) >3,000,000



Mechanical Specification





Unit: mm

Tolerance: ±0.2

For more information, contact your Apacer representative

Global Presence

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